

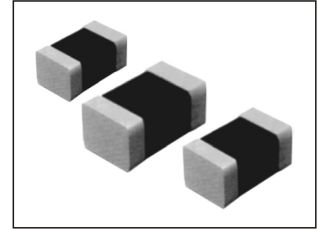
SURFACE-MOUNT MULTI-LAYER CHIP BEADS

FEATURES:

- Multilayer structure
- Closed magnetic circuit
- Avoids crosstalk
- Excellent magnetic shield
- Excellent solderability
- High reliability
- EMI/RFI suppression
- 20% impedance tolerance

COMMON APPLICATIONS:

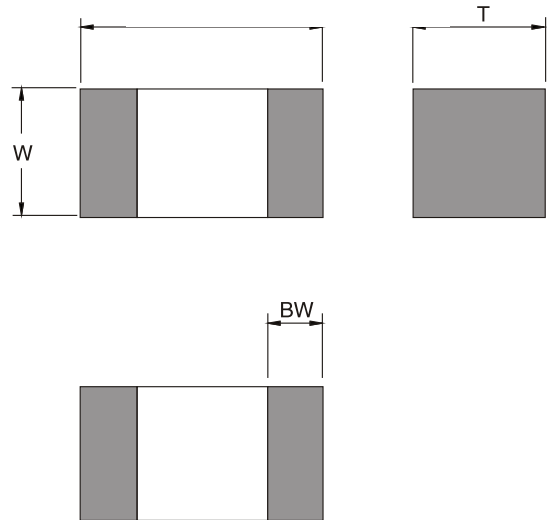
- Cellular Phones
- Mobil Radios
- Cordless Telephones
- Modems
- Global Positioning Systems
- Wireless Communications Equipment
- Network Systems
- Computer Products



ELECTRICAL CHARACTERISTICS:

Part Number	IMPEDANCE (Ω) AT 100 MHz	DCR (Ω) Max	IDC Max mA
SCB1005-050H	5	0.045	500
SCB1005-070H	7	0.045	500
SCB1005-110	11	0.05	500
SCB1005-190	19	0.05	300
SCB1005-260	26	0.15	300
SCB1005-310	31	0.20	300
SCB1005-360	36	0.20	300
SCB1005-600	60	0.35	200
SCB1005-800	80	0.40	200
SCB1005-121	120	0.50	150
SCB1005-151	150	0.55	150
SCB1005-181	180	0.60	150
SCB1005-221	220	0.70	100
SCB1005-301	300	0.80	100
SCB1005-501	500	1.1	100
SCB1005-601	600	1.3	100
SCB1005-801	800	1.4	50
SCB1005-102	1000	1.6	25
SCB1005-122	1200	1.8	25
SCB1608-050	5	0.05	1000
SCB1608-090	9	0.05	1000
SCB1608-110	11	0.05	1000
SCB1608-190	19	0.05	1000
SCB1608-260	26	0.06	500
SCB1608-310	31	0.06	500
SCB1608-600	60	0.12	300
SCB1608-700	70	0.12	300
SCB1608-800	80	0.12	300
SCB1608-101	100	0.20	200
SCB1608-121	120	0.20	200
SCB1608-151	150	0.20	200
SCB1608-181	180	0.30	200
SCB1608-221	220	0.30	200
SCB1608-301	300	0.35	150
SCB1608-501	500	0.40	150
SCB1608-601	600	0.45	100
SCB1608-801	800	0.50	100
SCB1608-102	1000	0.60	100
SCB1608-122	1200	0.80	100
SCB1608-152	1500	0.90	50
SCB1608-202	2000	1.20	50

CHARACTERISTICS:



DIMENSIONS IN: mm

Part Number	L	W	T	BW
SCB1005	1.0 ± 0.15	0.5 ± 0.15	0.5 ± 0.15	0.25 ± 0.1
SCB1608	1.6 ± 0.2	0.8 ± 0.2	0.8 ± 0.2	0.3 ± 0.2

TECHNICAL INFORMATION:

- Testing: Impedance vs. Frequency: HP 4195A
- Solderability: 90% of the terminal electrode shall be covered
Preheat: @ $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 60 seconds
Flux: Rosin, Dip for 10 seconds ± 1 second
- Thermal Shock: Impedance shall be within $\pm 20\%$ of initial value when temperature is -25°C and $+85^{\circ}\text{C}$ for 30 minutes for each 50 cycles
- Operating Temperature: -25°C to $+85^{\circ}\text{C}$
- Storage Temperature: -25°C to $+85^{\circ}\text{C}$

Note: All specifications subject to change without notice.

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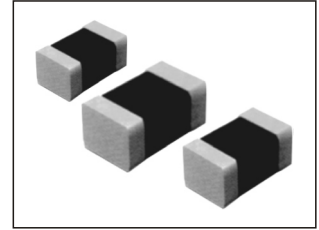
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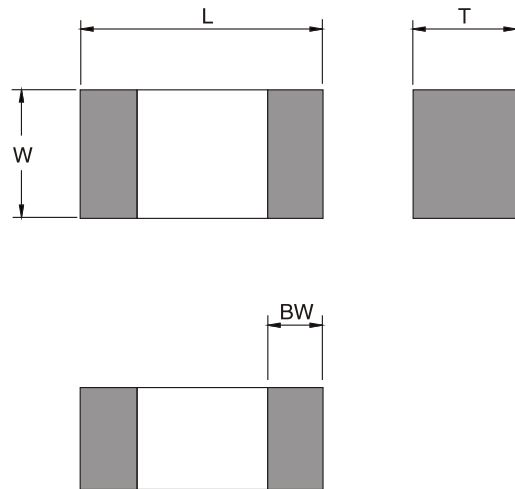
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ELECTRICAL CHARACTERISTICS:

Part Number	IMPEDANCE (Ω) AT 100 MHz	DCR (Ω) Max	IDC Max mA
SCB2012-070	7	0.20	600
SCB2012-110	11	0.20	600
SCB2012-190	19	0.20	600
SCB2012-260	26	0.20	400
SCB2012-310	31	0.20	400
SCB2012-360	36	0.20	400
SCB2012-600	60	0.25	400
SCB2012-700	70	0.25	400
SCB2012-800	80	0.25	400
SCB2012-101	100	0.25	400
SCB2012-121	120	0.25	300
SCB2012-151	150	0.25	300
SCB2012-181	180	0.25	300
SCB2012-221	220	0.25	300
SCB2012-301	300	0.25	300
SCB2012-501	500	0.35	200
SCB2012-601	600	0.40	200
SCB2012-801	800	0.40	150
SCB2012-102	1000	0.45	100
SCB2012-122	1200	0.06	100
SCB2012-151	1500	0.80	100
SCB2012-202	2000	0.90	50
SCB2012-222	2200	1.00	50
SCB2012-252	2500	1.20	50
SCB2012-302	3000	1.40	50
SCB3216-190	19	0.20	500
SCB3216-260	26	0.20	500
SCB3216-310	31	0.30	500
SCB3216-600	60	0.30	400
SCB3216-700	70	0.30	400
SCB3216-800	80	0.30	300
SCB3216-101	100	0.30	300
SCB3216-121	120	0.30	300
SCB3216-151	150	0.30	300
SCB3216-181	180	0.35	300
SCB3216-221	220	0.30	300
SCB3216-301	300	0.30	300
SCB3216-501	500	0.30	200
SCB3216-601	600	0.30	200
SCB3216-801	800	0.30	200
SCB3216-102	1000	0.30	200
SCB3216-122	1200	0.50	100
SCB3216-152	1500	0.60	100
SCB3216-202	2000	0.60	100
SCB3216-252	2500	0.80	100
SCB3216-302	3000	1.00	80

CHARACTERISTICS:



DIMENSIONS IN: mm

Part Number	L	W	T	BW
SCB2012	2.0 ± 0.2	1.2 ± 0.2	0.9 ± 0.2	0.5 ± 0.3
SCB3216	3.2 ± 0.2	1.6 ± 0.2	1.1 ± 0.2	0.5 ± 0.3

TECHNICAL INFORMATION:

- Testing: Impedance vs. Frequency: HP 4195A
- Solderability: 90% of the terminal electrode shall be covered
Preheat: @ $260^\circ\text{C} \pm 5^\circ\text{C}$ for 60 seconds
Flux: Rosin, Dip for 10 seconds ± 1 second
- Thermal Shock: Impedance shall be within $\pm 20\%$ of initial value when temperature is -25°C and $+85^\circ\text{C}$ for 30 minutes for each 50 cycles
- Operating Temperature: -25°C to $+85^\circ\text{C}$
- Storage Temperature: -25°C to $+85^\circ\text{C}$

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SCB3225,4516,4532 SERIES

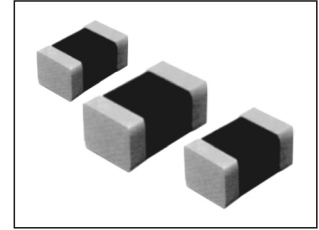
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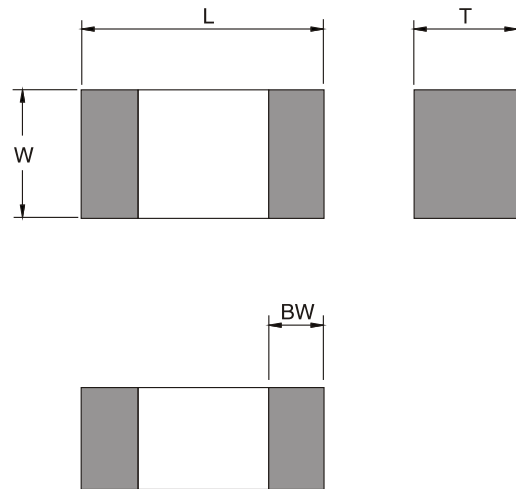
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ELECTRICAL CHARACTERISTICS:

Part Number	IMPEDANCE (Ω) AT 100 MHz	DCR (Ω) Max	IDC Max mA
SCB3225-190	19	0.20	500
SCB3225-260	26	0.20	500
SCB3225-310	31	0.20	500
SCB3225-600	60	0.30	400
SCB3225-700	70	0.30	400
SCB3225-800	80	0.30	300
SCB3225-900	90	0.30	300
SCB3225-121	120	0.30	300
SCB3225-151	150	0.30	300
SCB3225-221	220	0.30	300
SCB3225-301	300	0.30	300
SCB3225-501	500	0.30	200
SCB3225-601	600	0.30	200
SCB3225-801	800	0.30	200
SCB3225-102	1000	0.30	200
SCB3225-122	1200	0.50	100
SCB3225-152	1500	0.60	100
SCB3225-202	2000	0.60	100
SCB3225-190L	19	0.04	3000
SCB3225-260L	26	0.04	3000
SCB3225-310L	31	0.04	3000
SCB3225-600L	60	0.04	3000
SCB3225-700L	70	0.04	3000
SCB3225-800L	80	0.04	3000
SCB3225-900L	90	0.05	2000
SCB3225-121L	120	0.10	2000
SCB3225-151L	150	0.10	2000
SCB3225-301L	300	0.20	1000
SCB3225-501L	500	0.20	1000
SCB3225-601L	600	0.10	1000
SCB3225-801L	800	0.10	1000
SCB3225-102L	1000	0.50	500
SCB4516-800	80	0.30	300
SCB4516-101	100	0.10	300
SCB4516-151	150	0.30	300
SCB4516-250	25	0.30	500
SCB4516-700	70	0.30	300
SCB4516-121	120	0.30	300
SCB4516-131	130	0.30	300
SCB4516-600L	60	0.01	6000
SCB4516-750L	75	0.025	3000
SCB4516-800L	80	0.05	3000
SCB4516-121L	120	0.10	2000
SCB4516-151L	150	0.10	2000
SCB4516-102L	1000	0.15	1500
SCB4532-700	70	0.035	6000
SCB4532-800	80	0.050	6000
SCB4532-121	120	0.050	3000
SCB4532-151	150	0.050	3000

CHARACTERISTICS:



DIMENSIONS IN: mm

Part Number	L	W	T	BW
SCB3225	3.2 ± 0.2	2.5 ± 0.2	1.3 ± 0.2	0.5 ± 0.3
SCB4516	4.5 ± 0.2	1.6 ± 0.2	1.6 ± 0.2	0.5 ± 0.3
SCB4532	4.5 ± 0.2	3.2 ± 0.2	1.5 ± 0.2	0.5 ± 0.3

TECHNICAL INFORMATION:

- Testing: Impedance vs. Frequency: HP 4195A
- Solderability: 90% of the terminal electrode shall be covered
Preheat: @ 260°C ± 5°C for 60 seconds
Flux: Rosin, Dip for 10 seconds ± 1 second
- Thermal Shock: Impedance shall be within ± 20% of initial value when temperature is -25°C and +85°C for 30 minutes for each 50 cycles
- Operating Temperature: -25°C to +85°C
- Storage Temperature: -25°C to +85°C

Note: All specifications subject to change without notice.